

IPC CEMAC 2025

IPC Electronics Manufacturing Annual Conference 2025

Date: September 25-26, 2025

Venue: 2nd Floor, Crowne Plaza Shanghai Jinxiu

Address: No.399 Jinxiu Road, Pudong New Area, Shanghai, China

Organizer: IPC, Pudong New Area Association for Quality and Technology Shanghai

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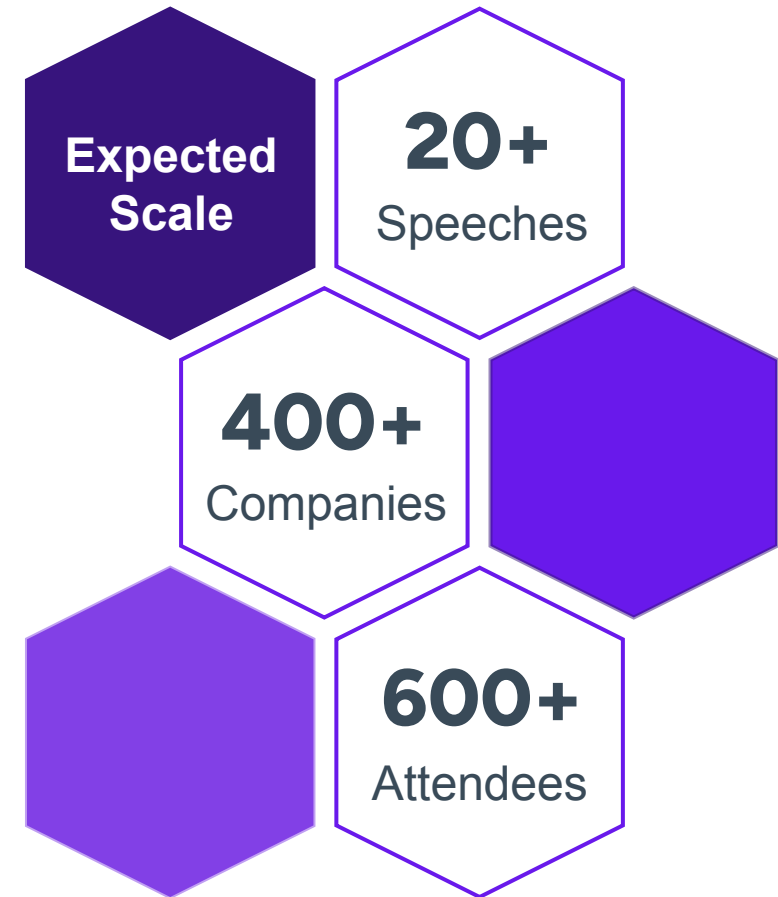
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About CEMAC

IPC CEMAC (IPC Electronics Manufacturing Annual Conference) is dedicated to promoting technological innovation, standardization, and international collaboration within the electronics industry. Through keynote, technical seminars, standards development task group, and special networking sessions, the conference serves as an efficient and professional international platform for experts, scholars, and business leaders in the field of electronics manufacturing.

IPC CEMAC 2025, themed **“Shaping a Sustainable Future”**, will spotlight key topics such as advanced packaging, emerging industries, PCB/PCBA technologies, AI and digital transformation, and ESG sustainability—leading the industry toward a more innovative, intelligent, and greener future.



Overview

■ Project Launch

Release of the IPC Annual Development Report on the Electronics Manufacturing Industry, along with the launch of new standards, training courses, and demonstration projects, collectively witnessing the industry's innovation and advancement.

■ Technical Forums

Four themed forums will be held, focusing on advanced packaging, emerging industries, PCB/PCBA technologies, AI and digital transformation, as well as green manufacturing and ESG sustainable development. These forums will explore cutting-edge technologies and industry trends, inspiring participants with forward-looking insights and fostering industry innovation and collaboration.

■ Committee Meeting

Focusing on key areas such as standards development, talent cultivation, automotive electronics, and intelligent manufacturing, these meetings will align with industry trends and market demands. Through case discussions, guideline development, and project collaboration, they aim to foster practical and actionable solutions—accelerating the transformation of the electronics manufacturing industry toward next-generation productivity.

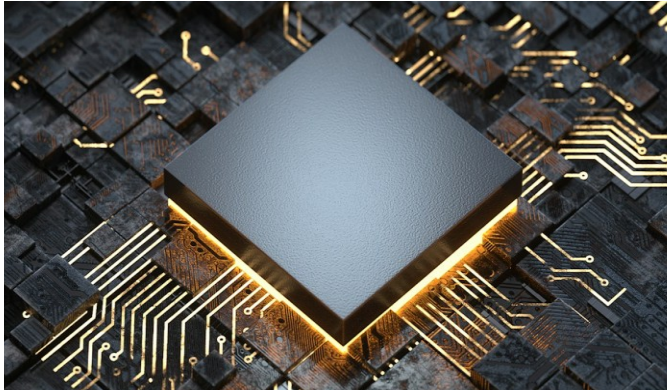
■ Standard Development Technical Meeting

These sessions will provide in-depth interpretation of the latest IPC standard revisions, focusing on the technical challenges and implementation bottlenecks encountered by enterprises. The goal is to promote the effective localization and practical application of standards.

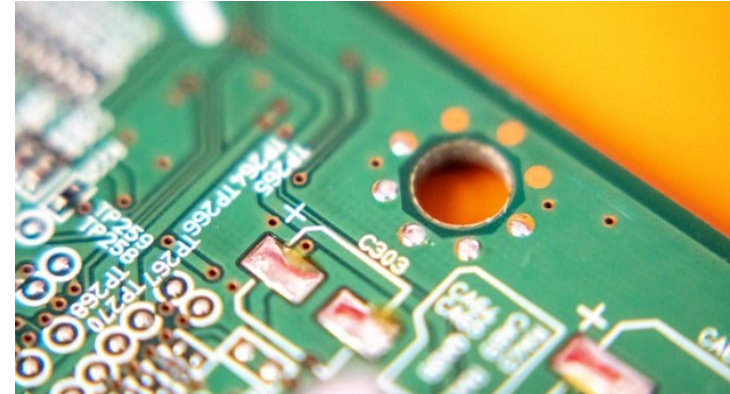
■ Special Events

The special events will be held to express appreciation and present recognitions to partners, committee members, and outstanding companies and individuals who have made significant contributions to the development of the industry.

Theme Forums



Advanced Packaging Technologies and
Future Ecosystem Development



Opportunities and Challenges for PCB & PCBA
Driven by Emerging Industries



Digital and Intelligent Transformation of
Electronics Manufacturing



ESG Sustainability Trends and Practices in
Electronics Manufacturing

Schedule at a Glance

	Theme Forum	Professional Committee Meeting	Standard Development Technical Meeting	Special Events
9/25 AM	Opening Ceremony and Keynote Speech Forum 1: Digital and Intelligent Transformation of Electronics Manufacturing	IPC CAEC China Automotive Electronics Steering Committee Meeting	IPC-6931 Requirements and Acceptance of Optical Module Printed Boards	Partner luncheon
9/25 PM	Forum 2: Opportunities and Challenges for PCB & PCBA Driven by Emerging Industries	IPC AESC Asia Education Steering Committee Meeting	IPC-2553 Model-Based Board-Level Virtual Verification Guidelines for Finite Element Analysis and Board-Level Reliability	
9/26 AM	Forum 3: Advanced Packaging Technologies and Future Ecosystem Development	IPC ASSC Asia Standards Steering Committee Meeting	IPC-1401B ESG Management System Standard IPC-CFX-2591-V2.0 Connected Factory Exchange(CFX) & IPC-HERMES-9852-1.6 The Global Standard for Machine-to-Machine Communication in SMT Assembly	
9/26 PM	Forum 4: ESG Sustainability Trends and Practices in Electronics Manufacturing	IPC CIMSC China Intelligent Manufacturing Steering Committee Meeting	IPC-7077 Requirements and Acceptance of Wire Bonding in the Microelectronic Assembly	Committee Reception IPC Member Appreciation and Award Dinner

Please note: The above schedule is for reference only. The final schedule is subject to the on-site arrangements.



Become a Sponsor

<https://go.ipc.org.cn//658623/2024-10-18/877jg>

Benefits	Premier Sponsor CNY 38,000	Supporting Sponsor CNY 10,800
Promotion on IPC official & partner platforms	√	√
Onsite display of company Logo (Main signage and agenda signage)	√	√
Booth area (Backdrop and table)	√	√
Attendee list (Information of Authorized Personnel)	√	√
Distribution of promotional materials	√	√
Customized invitation Poster	√	√
Acknowledgment and certificate presentation at the banquet	√	√
30-minute presentation	√	/
Display company logo on the main forum screen	√	/
Priority in booth selection	√	/
Complimentary banquet seats (Invitation Only)	4 seats	2 seats
Complimentary access to partnership luncheon (Invitation Only)	2 seats	/

Add-On Sponsorship Opportunities:

Lunch Sponsorship

Logo on lunch tickets and signage

**CNY 10,000 /
per session**

Banquet Sponsorship (Exclusive)

CNY 20,000

Company promo video before banquet, logo on banquet tickets and signage, and acknowledgment.

Banquet Gift Sponsorship

**CNY 10,000 or
gift equivalent**

Logo on banquet main screen, custom-printed gifts, and acknowledgment.

Booth Selection Guidelines

■ Booth Selection Priority: :

1. Priority by Level: Premier sponsors have priority over supporting sponsors.
2. Priority by Time: Sponsors who sign the contract earlier have priority over those who sign later.

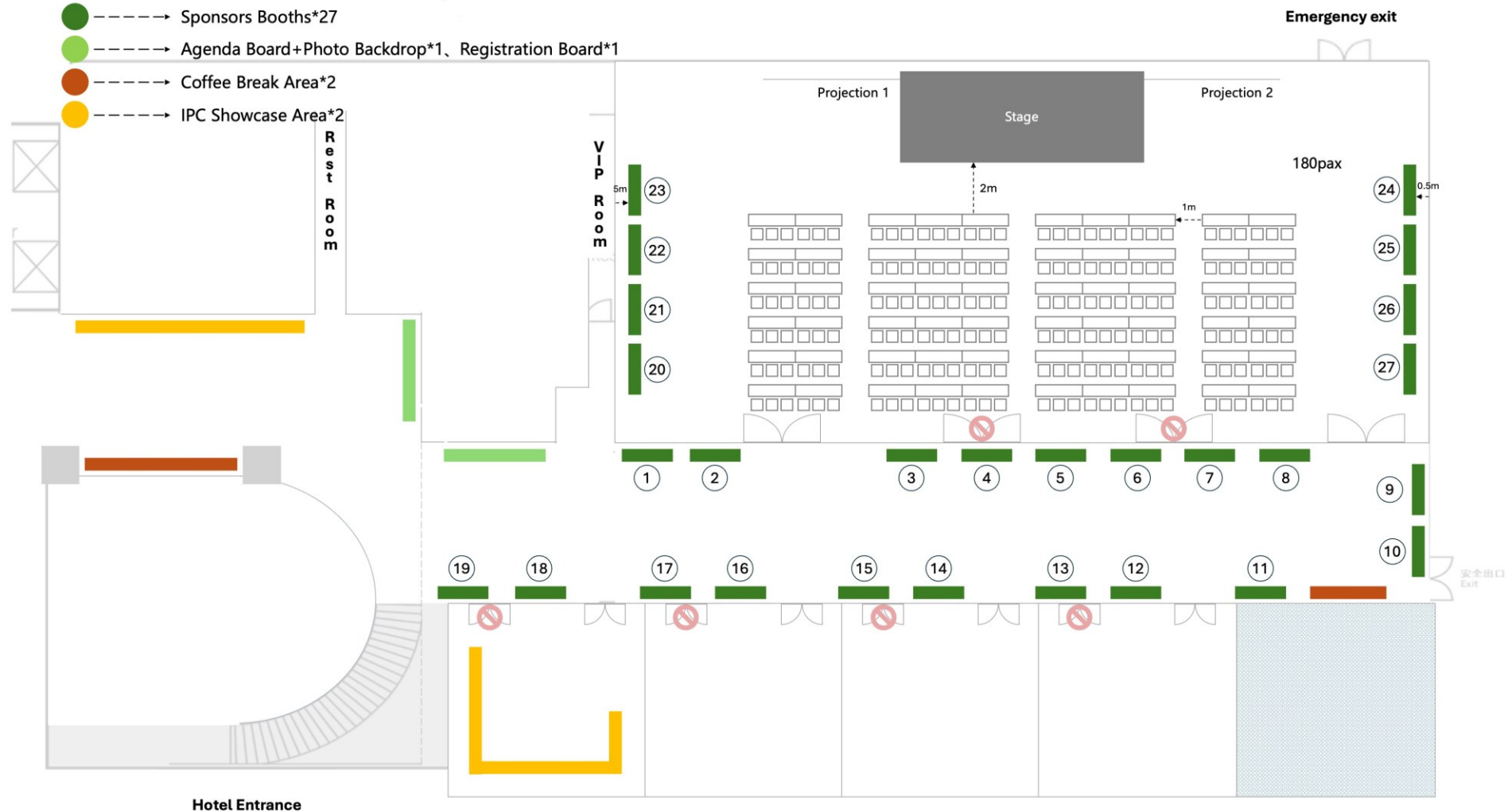
■ Booth Selection Schedule:

1. Premier sponsors who complete the contract signing before July 31 may select their booths.
2. On July 31, supporting sponsors who have signed the contract may select their booths.
3. For sponsors who complete the contract signing after July 31, booth locations will be assigned by IPC.

Notes:

1. The signing time is based on the timestamp when IPC receives the sponsor's stamped contract. Any disputes will be resolved through communication with the CEMAC committee.
2. If the sponsor loses priority due to their own reasons (e.g., late booth selection, cancellation of sponsorship), their position will automatically move down to the next sponsor of the same level.
3. The CEMAC committee reserves the right to make minor adjustments to the booth layout based on onsite conditions, safety, and visitor flow, and will promptly notify sponsors of any final changes to their confirmed booths.

Floorplan



Call for Paper

<https://cemac.ipc.org.cn/callforpaper>



- Award-winning papers will be recommended for publication in leading industry journals.
- Selected speakers will be invited to present at the CEMAC Technical Forums.
- Showcase technical achievements and enhance your personal and corporate visibility within the industry.
- Engage directly with global industry leaders to expand your professional and academic network.
- Attend the CEMAC Member Appreciation and Recognition Ceremony to celebrate moments of honor.

Visitor Registration

<https://go.ipc.org.cn/cemac2025>



- Gain in-depth insights into the latest technologies, standards, and application trends in the electronics manufacturing industry, enhancing professional competence and industry awareness.
- Exchange ideas and share experiences with experts, scholars, and researchers from diverse backgrounds across the industry.
- Explore innovative solutions and technical achievements from leading enterprises, creating potential collaboration opportunities.

Topics of Interest

Advanced Packaging Technologies and Future Ecosystem Development

- Ecosystem and Development Strategies for Advanced Packaging
- Innovation in Advanced Packaging Materials and Process Assurance
- Core Technologies in High-Density Integration and Miniaturized Packaging
- Thermal Management and Power Density Challenges in Advanced Packaging
- Collaborative Design and Application Innovation of System-in-Package (SiP)
- Quality Assurance and Standardization Research in Advanced Packaging

Digital and Intelligent Transformation of Electronics Manufacturing

- Innovative Integration of Electronics Manufacturing and Intelligent Technologies
- Intelligent Decision-Making and Process Optimization in Electronics Manufacturing
- Data-Driven Applications in Smart Electronics Manufacturing
- AI-Driven Transformation and Application of Electronics Manufacturing
- Smart Factory Solutions and Representative Case Studies
- Standard Systems and Application Practices for Future Factories

Opportunities and Challenges for PCB & PCBA Driven by Emerging Industries

- Evolution Trends in Advanced Manufacturing and Processes
- Technological Innovation and Applications of Advanced Materials
- Breakthroughs and Practical Approaches in Inspection Technologies
- Reliability Challenges and Solutions in Extreme Application Scenarios
- Research Achievements in High-Reliability Testing
- Application Practices and Case Studies of IPC Assembly Standards

ESG Sustainability Trends and Practices in Electronics Manufacturing

- ESG Management Directions and Best Practices in Electronics Manufacturing
- ESG Compliance Challenges and Strategies of Export Enterprises
- ESG Sustainability Reporting Challenges of Listed Companies
- Supply Chain DeCarbon Innovative Practices in Electronics Manufacturing
- Green and Clean Chemical Management in Electronics Manufacturing
- Green Electronic Materials for Circular Economy and Low-Carbon Transition

Please Note: Comprehensive list but does not claim to be definitive. Other appropriate topics will be considered.

Abstract Submission Link: <https://cemac.ipc.org.cn/callforpaper>

To learn more IPC CEMAC 2025 details, please visit: <https://cemac.ipc.org.cn/>. If you have any question about abstracts submission, please contact Mr. Will ZHAO at willzhao@electronics.org

SHAPING A SUSTAINABLE FUTURE

**IPC CEMAC
2025**

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